

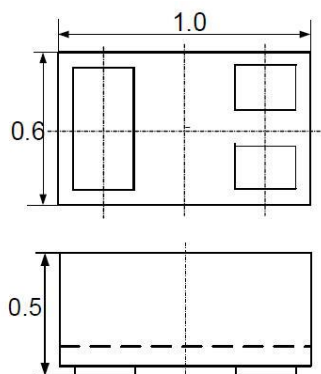
Description

The ESD0531P1 is an uni-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. The ESD0531P1 has an ultra-low capacitance with a typical value at 0.6pF, and complies with the IEC 61000-4-2 (ESD) with $\pm 25\text{kV}$ air and $\pm 20\text{kV}$ contact discharge. It is assembled into an ultra-small 1.0x0.6x0.5mm lead-free DFN package. The small size, ultra-low capacitance and high ESD surge protection make SEH0531P1 an ideal choice to protect cell phone, digital visual interfaces and other high speed ports.

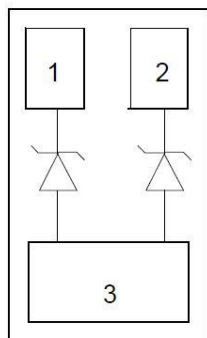
Features

- Ultra small package: 1.0x0.6x0.5mm
- Ultra low capacitance: 0.5pF typical
- Working voltage: 5V
- Low clamping voltage
- 3-pin leadless package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: $\pm 25\text{kV}$
Contact discharge: $\pm 20\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 5A (8/20us)
- RoHS Compliant

Dimensions & Symbol (Unit: mm Max)



Package Dimensions



Circuit and Pin Schematic

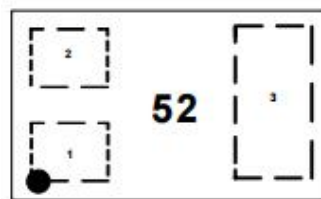
Mechanical Characteristics

- Package: DFN1006-3 (1.0×0.6×0.5mm)
- Lead Finish: NiPdAu
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Applications

- Cellular Handsets and Accessories
- Display Ports
- MDDI Ports
- USB 2.0 and 3.0 Ports
- HDMI 1.3 and 1.4
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports
- Notebook Computer
- IEEE 1394

Marking Information



Details marking code reference specification of approval list

Ordering Information

Part Number	Packaging	Reel Size
ESD0531P1	10000/Tape & Reel	7 inch

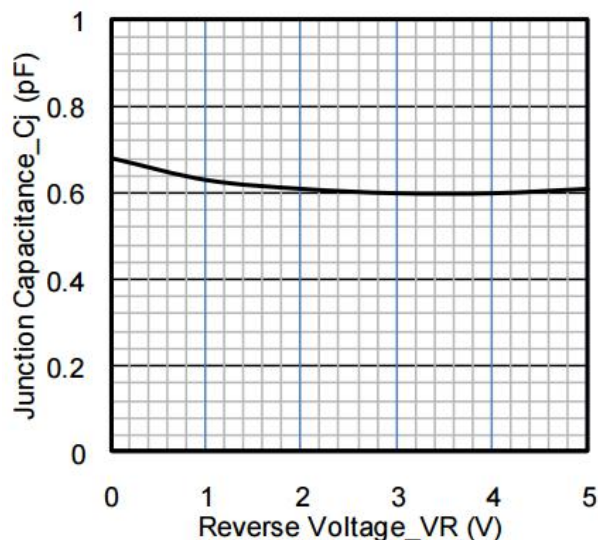
Absolute Maximum Ratings (T_A=25°C)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P _{ppp}	75	W
Peak Pulse Current (8/20μs)	I _{pp}	5	A
ESD per IEC 61000-4-2 (Air)	VESD	±25	kV
ESD per IEC 61000-4-2 (Contact)		±20	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

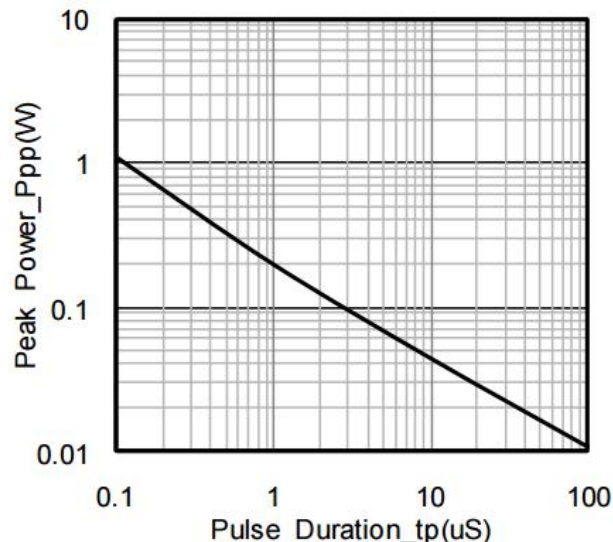
Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			5	V	Pin 1 or pin 2 to pin 3 and between pin 1 and pin 2
Breakdown Voltage	VBR	6			V	I _T = 1mA, pin 1 or pin 2 to pin 3 and between pin 1 and pin 2
Reverse Leakage Current	IR			0.5	uA	VRWM = 5V, Pin 1 or pin 2 to pin 3 and between pin 1 and pin 2
Clamping Voltage	VC			10	V	I _{PP} = 1A (8 x 20uS pulse), pin 1 or pin 2 to pin 3
Clamping Voltage	VC			15	V	I _{PP} = 5A (8 x 20uS pulse), pin 1 or pin 2 to pin 3
Junction Capacitance	C _J		0.4	0.6	pF	VR = 0V, f = 1MHz, between pin 1 and pin 2
Junction Capacitance	C _J		0.8		pF	VR = 0V, f = 1MHz, pin 1 or pin 2 to pin 3

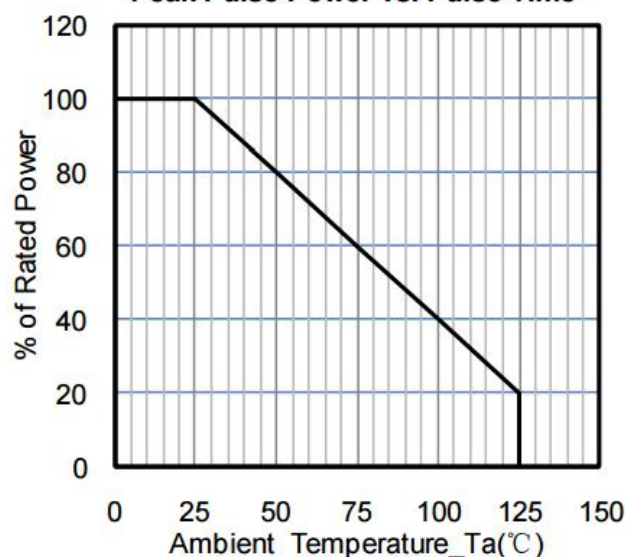
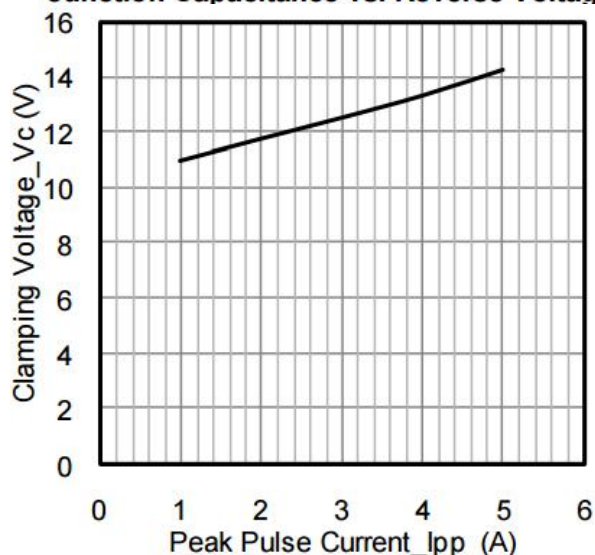
Typical Performance Characteristics (T_A=25°C unless otherwise Specified)



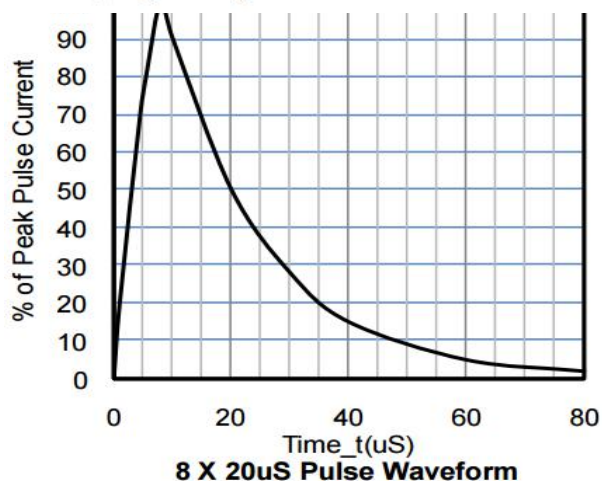
Junction Capacitance vs. Reverse Voltage



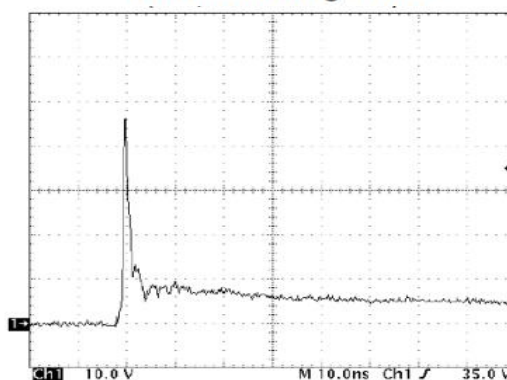
Peak Pulse Power vs. Pulse Time



Clamping Voltage vs. Peak Pulse Current



Power Derating Curve

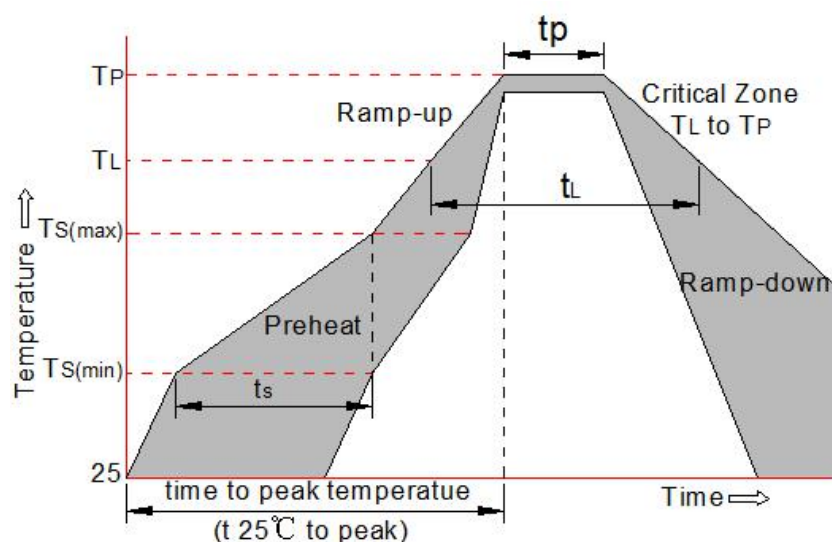


ESD Clamping Voltage

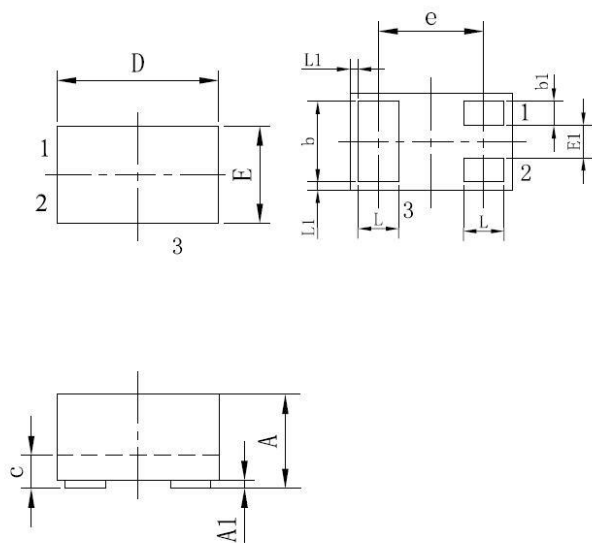
8 kV Contact per IEC61000-4-2

Soldering Parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_p)		8 min. Max
Do not exceed		+260℃

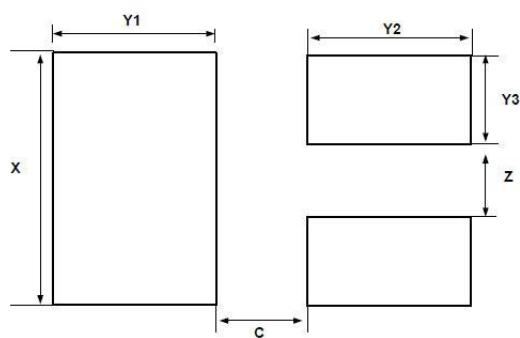


Package Mechanical Data



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
b1	0.10	0.15	0.20	0.004	0.006	0.008
c	0.12	0.15	0.18	0.005	0.006	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65 BSC			0.026 BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
E1	0.15	0.20	0.25	0.006	0.008	0.010
L	0.20	0.25	0.30	0.008	0.010	0.012
L1	0.05REF			0.002REF		

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	0.25	0.010
X	0.65	0.024
Y1	0.50	0.020
Y2	0.50	0.020
Y3	0.25	0.010
Z	0.20	0.008